

Title (en)

A resin encapsulated device and method of manufacture

Title (de)

Vergussgekapselfte Vorrichtung und Verfahren zur Herstellung

Title (fr)

Dispositif encapsulé en résine et procédé de fabrication

Publication

EP 1684316 A1 20060726 (EN)

Application

EP 05250267 A 20050120

Priority

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Abstract (en)

A resin encapsulated device (1) comprising a housing (2) defining a hollow body, a sensitive component (4) at least partly located within the housing, a resin material provided within the housing to at least partially encapsulate the component, characterised by a rigid buffer element (5) embedded within the resin material adjacent at least one component to prevent the origination of cracks within the resin material and/or to prevent cracks which might propagate within the resin material from reaching the component.

IPC 8 full level

H01F 27/32 (2006.01); **H01F 38/12** (2006.01); **H01F 41/00** (2006.01)

CPC (source: EP)

H01F 41/005 (2013.01); **H01F 27/306** (2013.01)

Citation (search report)

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Designated contracting state (EPC)

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